

## Probing The Silicon Strip Sensors

We want to probe the silicon sensor, pre-diced (when it is on the wafer) and diced (after cutting). The sensor dimensions are 62.00x62.00 mm, the wafer diameter is 100.00mm.

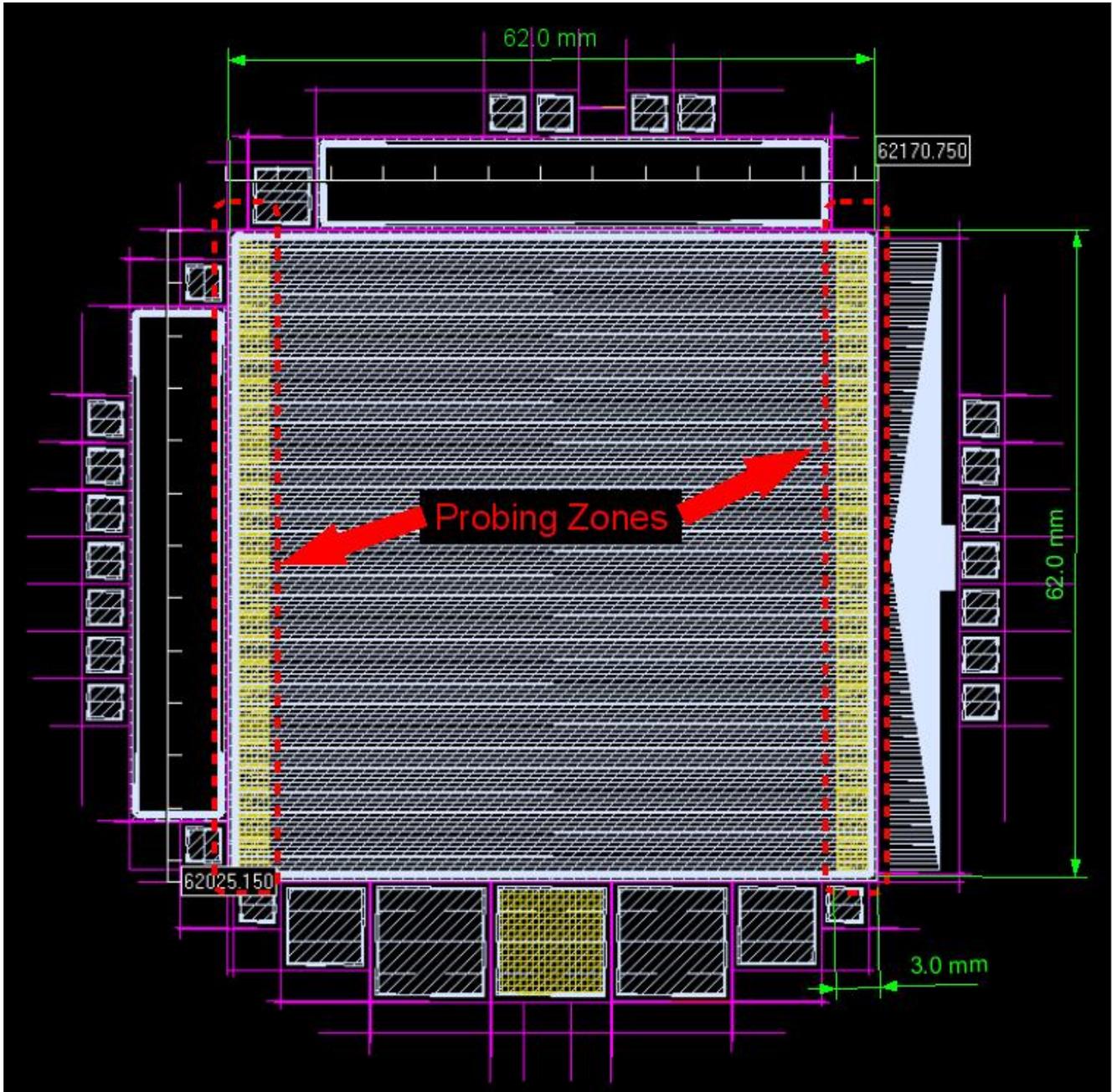
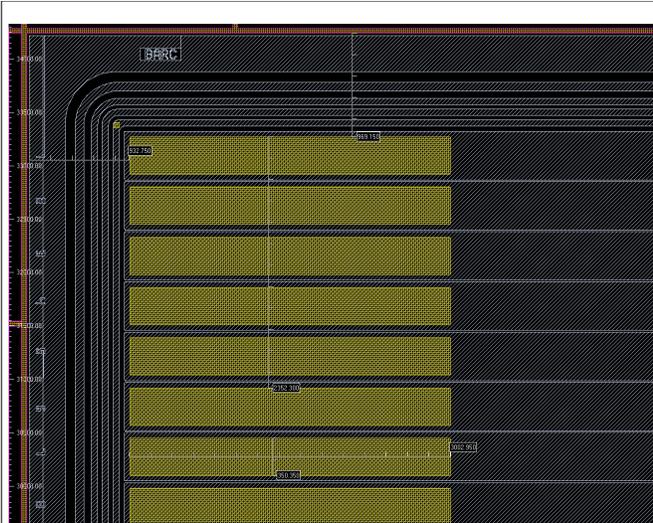
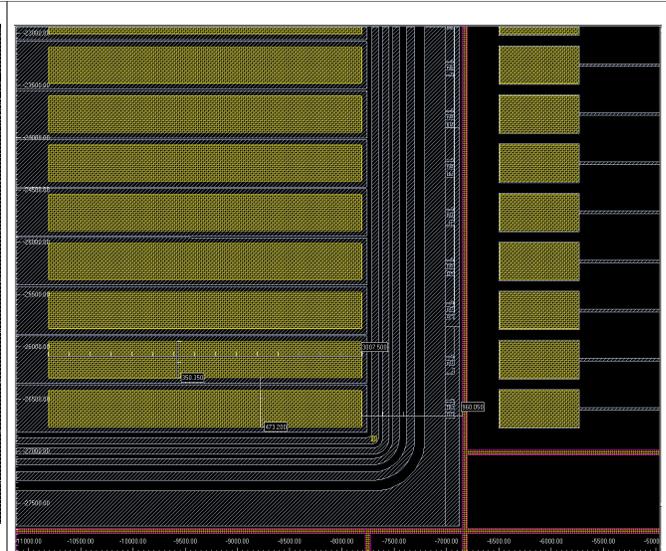


Fig. 1: The drawing of the wafer. The two identical probing zones are yellow areas on the left and right sides of the sensor.



*Fig. 2: The zoomed drawing of the upper-left corner of the sensor. The pads (yellow) have dimension 3.00x0.35 mm and they are spaced vertically with the 0.470mm pitch.*



*Fig. 3: The zoomed drawing of the lower-right corner of the sensor. The arrangement of pads is identical to the left side of the sensor.*

*The yellow pads are the area where the probing needles should contact the sensor. The pads dimensions are 3.00x0.35 mm and they are spaced vertically with 0.470mm pitch.*

*The probe card should have 128 needles, spaced in-line with the pitch size of 0.470 mm. The signals from the needles should be routed to two HD68 connectors (SCSI-III type) (<http://search.digikey.com/scripts/DkSearch/dksus.dll?Detail?name=A23756-ND>) located at the edge of the card.*